

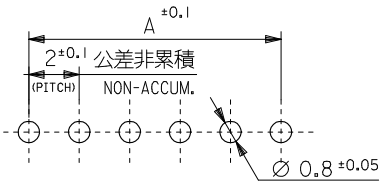
注記 NOTES

1. 嵌合相手 : 51065 シリーズ
MATE WITH : 51065 SERIES
2. 材質 MATERIAL
ウエハー : ポリアミド . UL94V-0
WAFER : PA , UL94V-0
ピン : 黄銅, 金メッキ
PIN : BRASS, GOLD (Au) PLATING
3. キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.

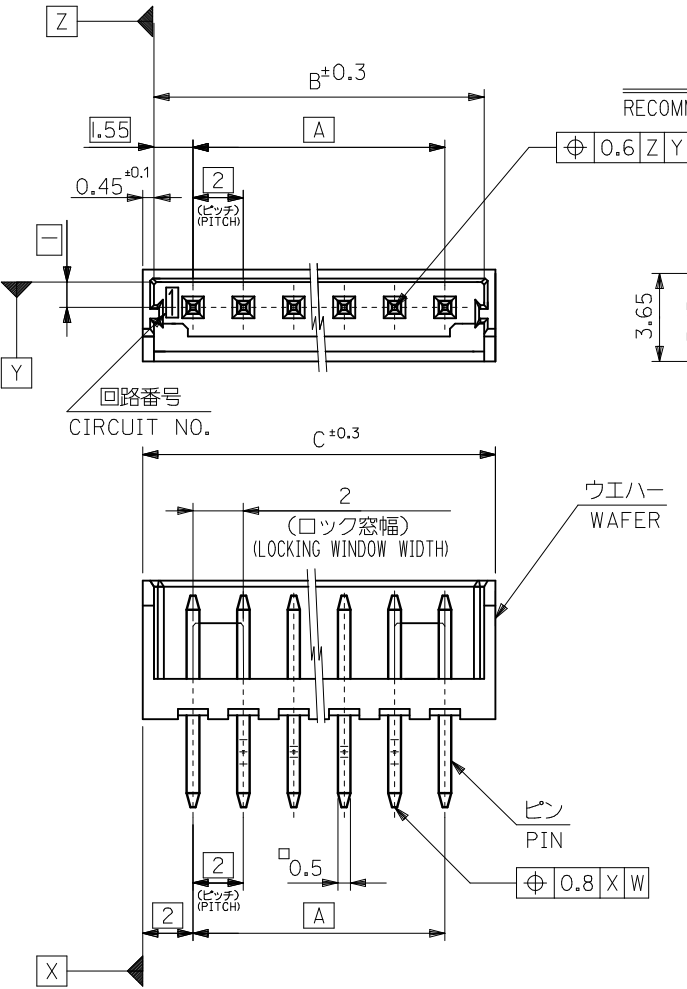
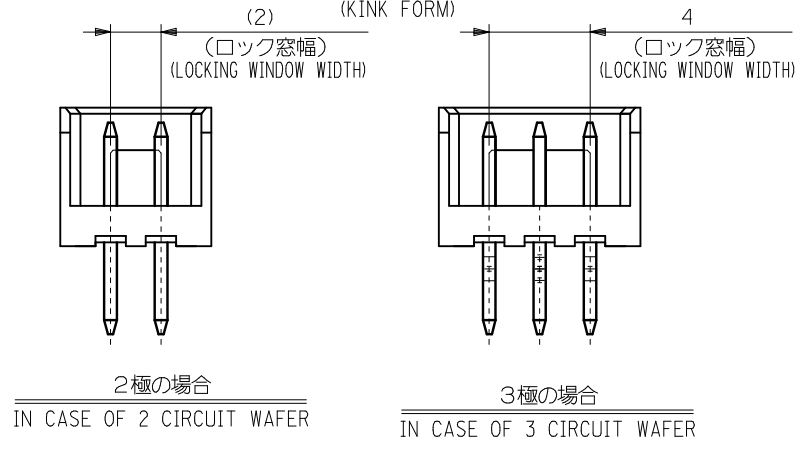
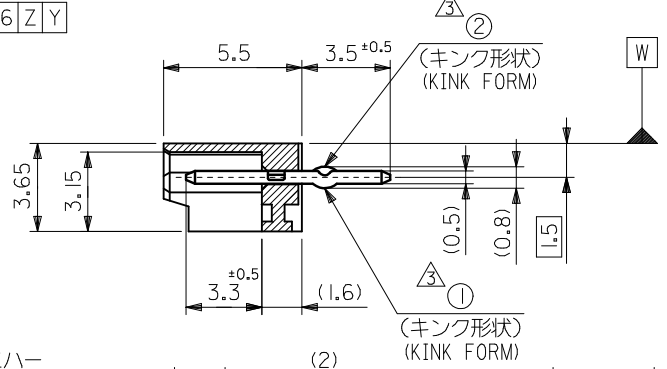
極数 CKT	回路番号 CKT NO.							
	1	2	3	4	5	N-2	N-1	N
6 極以上 MORE THAN 6 CKT	—	①	②	—	—	②	①	—
5 極 5 CKT	①	②	—	②	①			
4 極 4 CKT	①	②	②	①				
3 極 3 CKT	①	②	①					

4. 本製品は、53253-**70の金メッキ品です。
THIS PRODUCT IS AU PLATING OF 53253-**70.
5. 梱包仕様 PACKAGING
502603-**70 トレー TRAY

32	31.1	28	502603-1570	15
30	29.1	26	-1470	14
28	27.1	24	-1370	13
26	25.1	22	-1270	12
24	23.1	20	-1170	11
22	21.1	18	-1070	10
20	19.1	16	-0970	9
18	17.1	14	-0870	8
16	15.1	12	-0770	7
14	13.1	10	-0670	6
12	11.1	8	-0570	5
10	9.1	6	-0470	4
8	7.1	4	-0370	3
6	5.1	2	502603-0270	2
C	B	A	MATERIAL NO.	極数
MODEL NO.			502603-**70	



基板取付穴寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REFERENCE)



REVISED	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	
	0.25 UNDER	0.25 OVER	UNDER	±0.03	MM ONLY	5:1	METRIC	THIRD ANGLE PROJECTION
EC NO: J2017-0462	0.5 UNDER	1.0 UNDER	±0.05	±0.1	DRAWN BY	DATE	TITLE	
2017/02/17	1.0 OVER	30 UNDER	±0.2	±0.25	YMAEDA	2007/03/30	NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE-	
DRWN:KUSATO	30 OVER	ANGULAR ±3 °	±0.3	±0.3	CHECKED BY	DATE	molex	
2017/02/17					KTOYOTA	2007/03/30	DOCUMENT NO.	
CHKD:AIDA					APPROVED BY	DATE	SD-502603-001	
2017/03/02					NUKITA	2007/03/30	SHEET NO.	
APPR:TKANEKO					MATERIAL NO.		1 OF 1	
					SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	